

NOTES:

1. MATERIAL:

HOUSING:LCP,UL94V-0,COLOR:BLACK.  
 TERMINAL:COPPER ALLOY.  
 PICK AND PLACE COVER:LCP.  
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.  
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION. AND DATE-CODE \*YMDLS\*  
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. LGA1366 TO BE INDICATED IN THIS AREA.

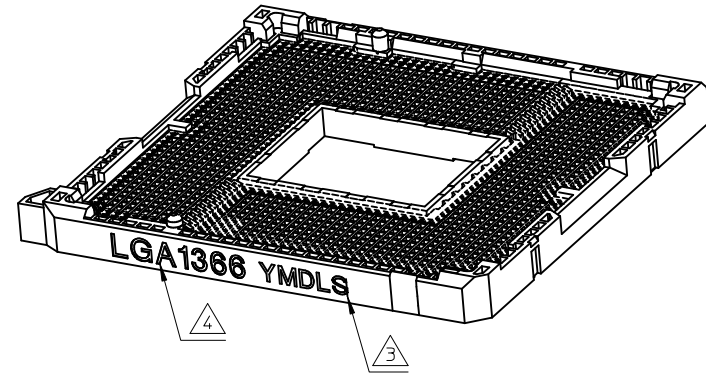
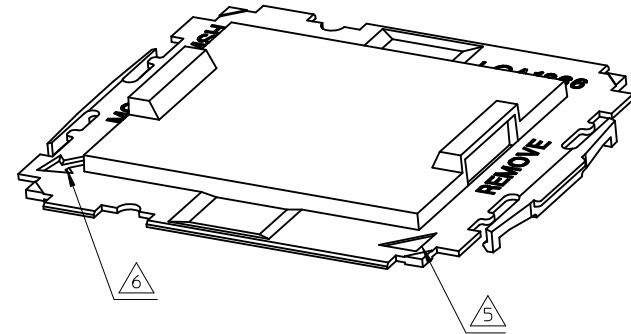
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 475940001/0002 COMPLIANT TO RoHS  
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

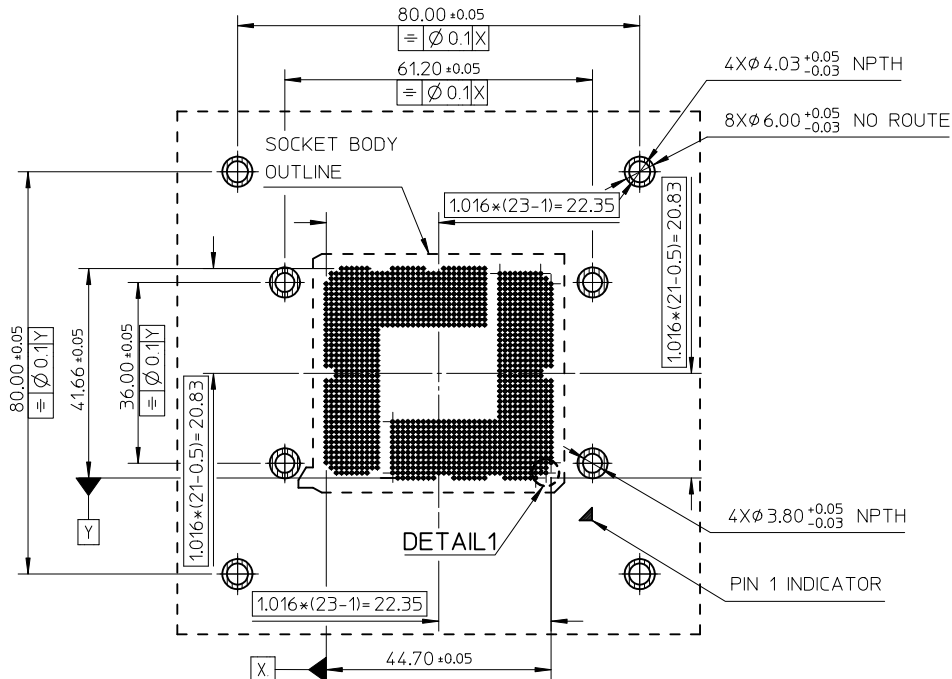


LGA1366 SOCKET PART NUMBER LIST				
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT
475940002	GENERAL	30u*(0.76um)	LEAD FREE	YES
475940001	GENERAL	15u*(0.38um)		

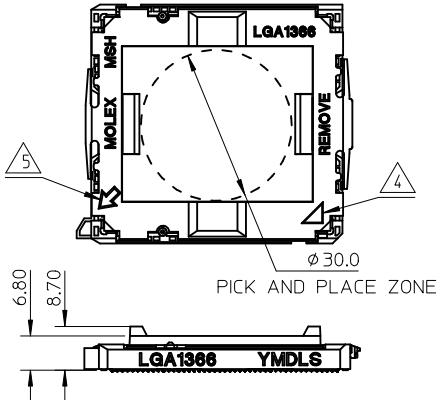
ENTER DESCRIPTION EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN 2011/12/07 2011/12/14	DESCRIPTION REV 6	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		$F_A=0$ $F_B=0$ $F_C=0$	mm      INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1°	MM ONLY	2:1	METRIC	
			DRAWN BY: WFDENG      DATE: 2008/09/16 CHECKED BY: JKACHLIC      DATE: 2008/09/16 APPROVED BY: AYIN      DATE: 2010/10/22	TITLE	LGA1366 SOCKET FULL ASSEMBLY		
		MATERIAL NO. SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-47594-001 SHEET NO. 1 OF 3				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



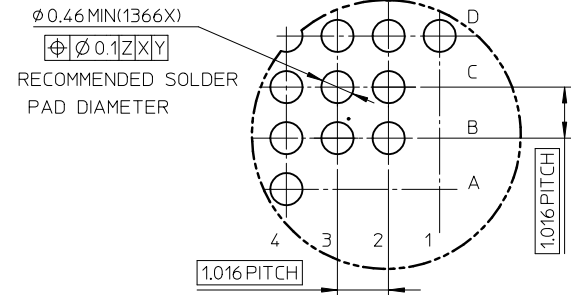
10 9 8 7 6 5 4 3 2 1



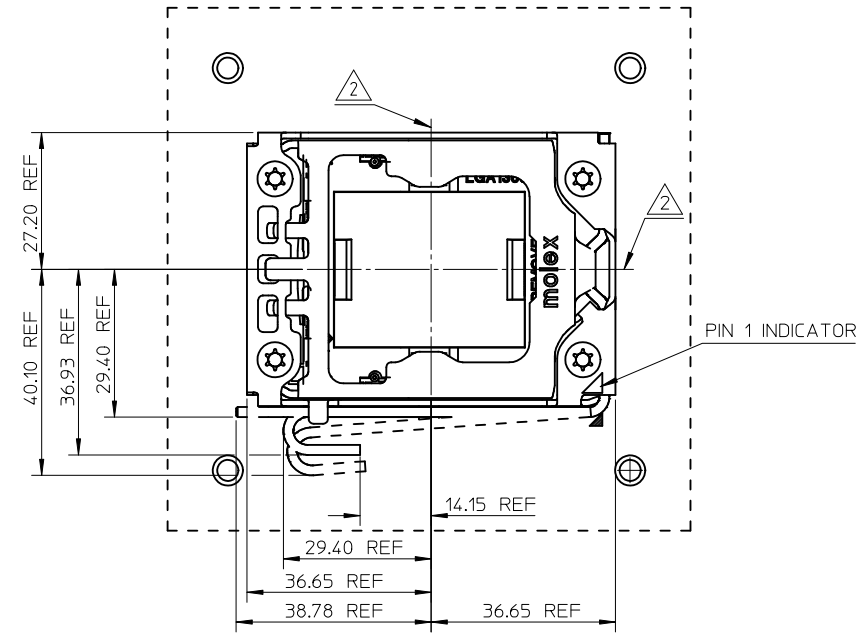
RECOMMEND PCB LAYOUT THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
  - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
  - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
  - SOCKET PIN 1 INDICATOR.
  - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
  - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.



DETAIL1 SCALE 10:1



SOCKET ON PCB(FOR REFERENCE ONLY) LOAD PLATE IS NOT LOCKED

<b>ENTER DESCRIPTION</b> EC NO: SH2012-0177 DRWN: ZHANG11 CHKD: APPR: AYIN 2011/12/07 2011/12/14	<b>QUALITY SYMBOLS</b> F=0 F=0 F=0	<b>GENERAL TOLERANCES (UNLESS SPECIFIED)</b>		<b>DIMENSION STYLE</b> MM ONLY	<b>SCALE</b> 1:1	<b>DESIGN UNITS</b> METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± ---	mm INCH	DRAWN BY: WFDENG CHECKED BY: JKACHLIC APPROVED BY: AYIN MATERIAL NO.	DATE: 2008/09/16 DATE: 2008/09/16 DATE: 2010/10/22	TITLE: LGA1366 SOCKET FULL ASSEMBLY	MOLEX INCORPORATED	SHEET NO. 3 OF 3
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	DOCUMENT NO. SD-47594-001	MOLEX INCORPORATED		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2 1

NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.  
 TERMINAL:COPPER ALLOY.  
 PICK AND PLACE COVER:LCP.  
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

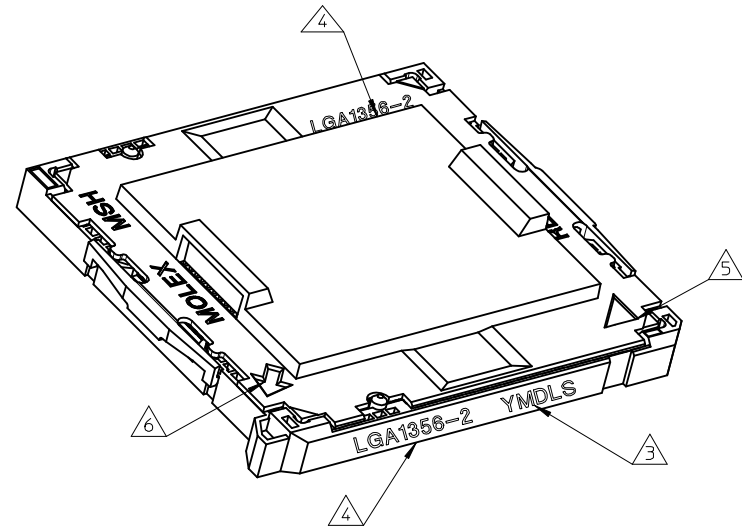
SEE TABLE FOR GOLD ON CONTACT AREA.  
 1.27 MICROMETER NICKEL UNDERPLATE.

- 3. DATE-CODE LOCATION. AND DATE-CODE \*YMDLS\* IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)
- 4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

- 7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.
- 8. PRODUCT PACKAGE PK-47594-003 APPLIES.
- 9. THE PARTS 47594\*001/\*002 COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



LGA1356 SOCKET PART NUMBER LIST					PART NAME	REMARK
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT		
475943001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-2(B2)	DIM.A=12.85
475943002	GENERAL	30u*(0.76um)				

RELEASED EC NO: SH2013-0064 DRWN: YZHENG 2012/06/12 CHKD: APPR: AYIN 2013/02/04	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		$F_A=0$ $F_C=0$ $F_B=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 1°	MM ONLY	2:1	METRIC	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE JZHANG11 2010/2/10 CHECKED BY DATE APPROVED BY DATE AYIN 2011/07/12	TITLE LGA1356 SOCKET FULL ASSEMBLY		
				MATERIAL NO. SEE TABLE SIZE A3	MOLEX INCORPORATED DOCUMENT NO. SD-47594-100		SHEET NO. 1 OF 3





NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.  
 TERMINAL:COPPER ALLOY.  
 PICK AND PLACE COVER:LCP.  
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.  
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION, AND DATE-CODE "YMDLS"  
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

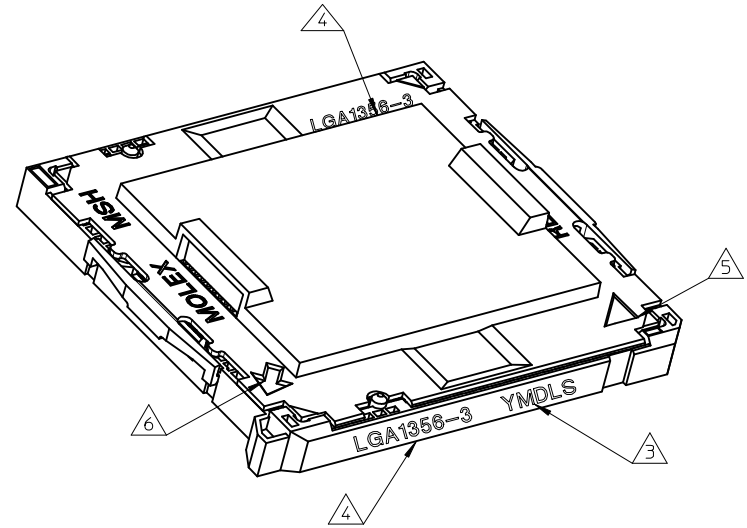
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 47594\*001/\*002 COMPLIANT TO RoHS  
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

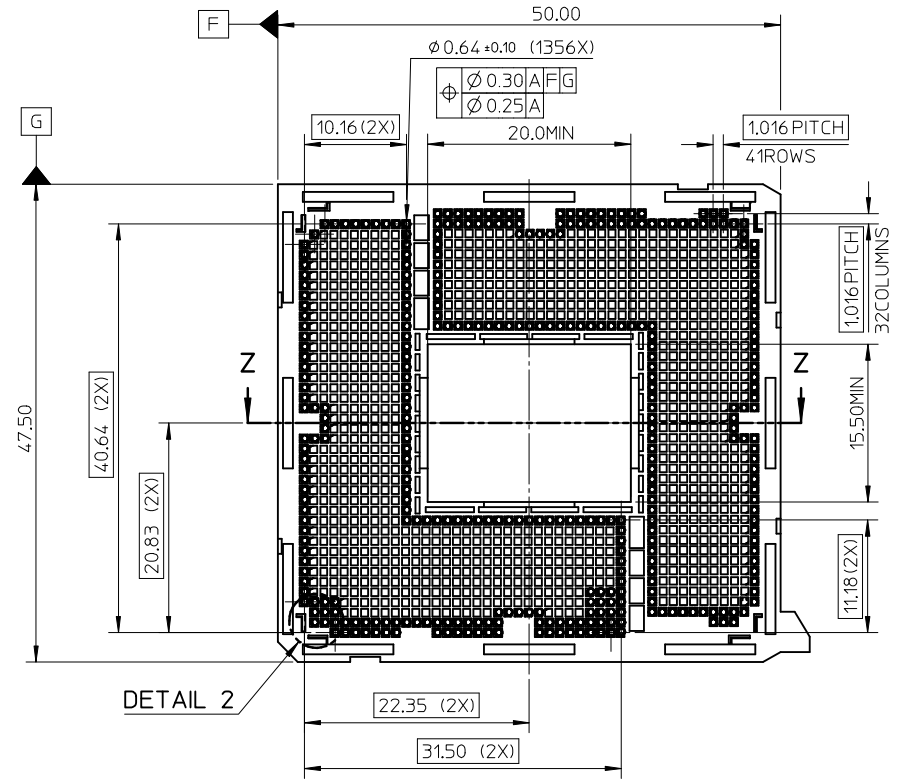
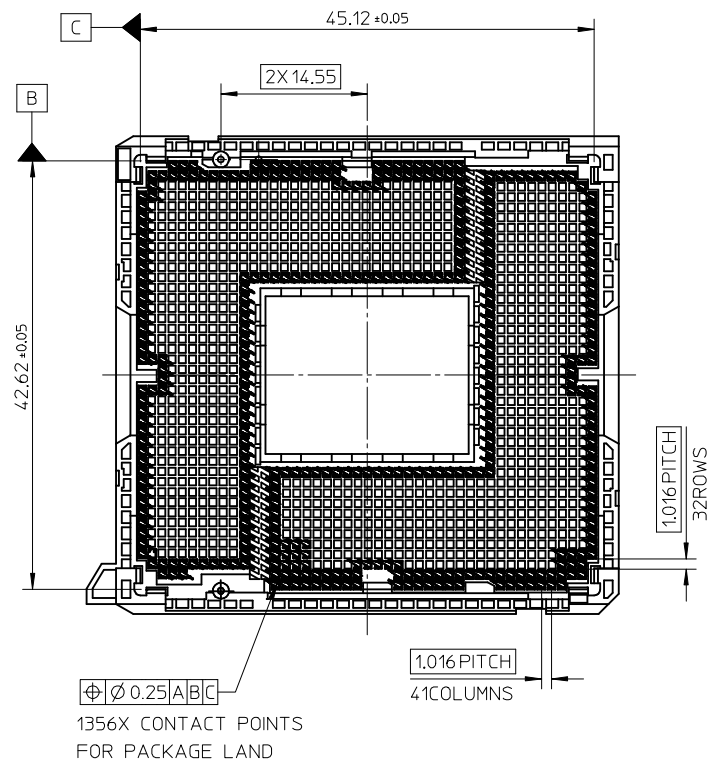


LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u*(0.76um)			

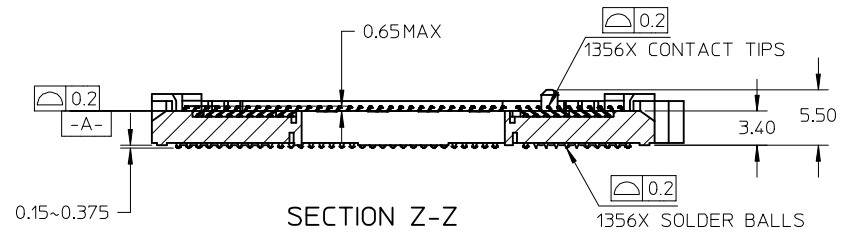
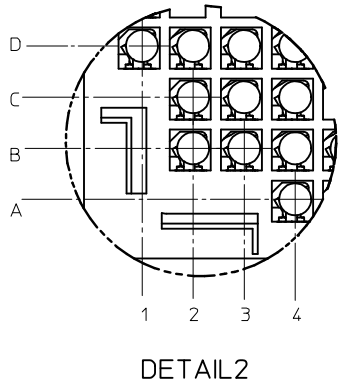
NEW RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/09/24 CH'KD: APPR: AYIN 2013/02/04 REV 1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	$F_{\square}=0$	mm	INCH	MM ONLY	2:1	METRIC		
	$F_{\square}=0$	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE		LGA1356-3 SOCKET(B3) FULL ASSEMBLY
	$F_{\square}=0$	2 PLACES ± 0.20 ± ---	1 PLACE ± 0.25 ± ---	YXZHENG	2012/09/24	SEE TABLE		
	0 PLACE ± --- ± ---	ANGULAR ± 1 °	CHECKED BY	DATE	APPROVED BY	DATE		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	AYIN	2013/02/04	MATERIAL NO.	DOCUMENT NO.		SHEET NO.
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			1 OF 3

10 9 8 7 6 5 4 3 2 1

F E D C B A



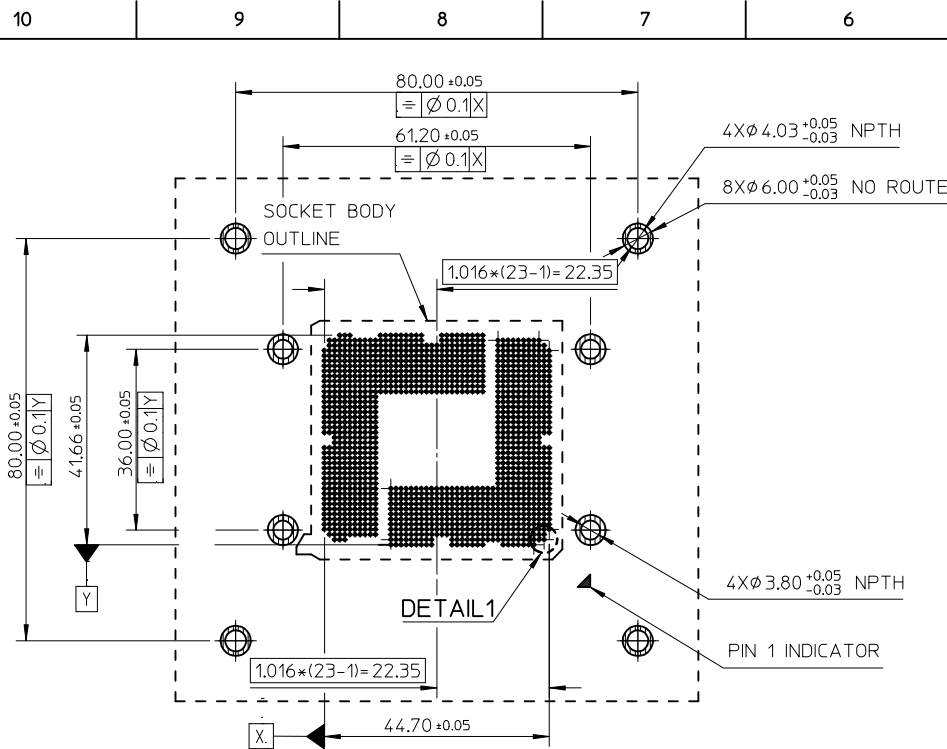
DETAIL 2



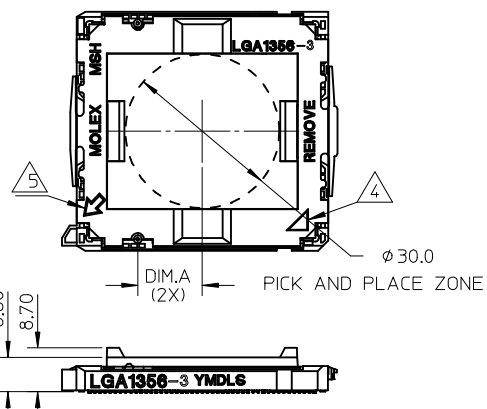
<b>NEW RELEASED</b> EC NO: SHZ013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_C=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± --- ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY: YXZHENG CHECKED BY: APPROVED BY: AYIN MATERIAL NO. DATE: 2012/09/24 DATE: 2013/02/04	SCALE 2:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY <b>molex</b> SEE PAGE 1 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	DOCUMENT NO. SD-47594-200 SHEET NO. 2 OF 3
	REV 1	DESCRIPTION	SIZE A3	DATE: 2012/09/24	DATE: 2013/02/04	DATE: 2013/02/04
	NEW RELEASED	EC NO: SHZ013-0064	DRWN: YXZHENG	CHKD:	APPR: AYIN	DATE: 2012/09/24
	2012/09/24	2013/02/04	DATE: 2013/02/04	DATE: 2013/02/04	DATE: 2013/02/04	DATE: 2013/02/04

9 8 7 6 5 4 3 2 1

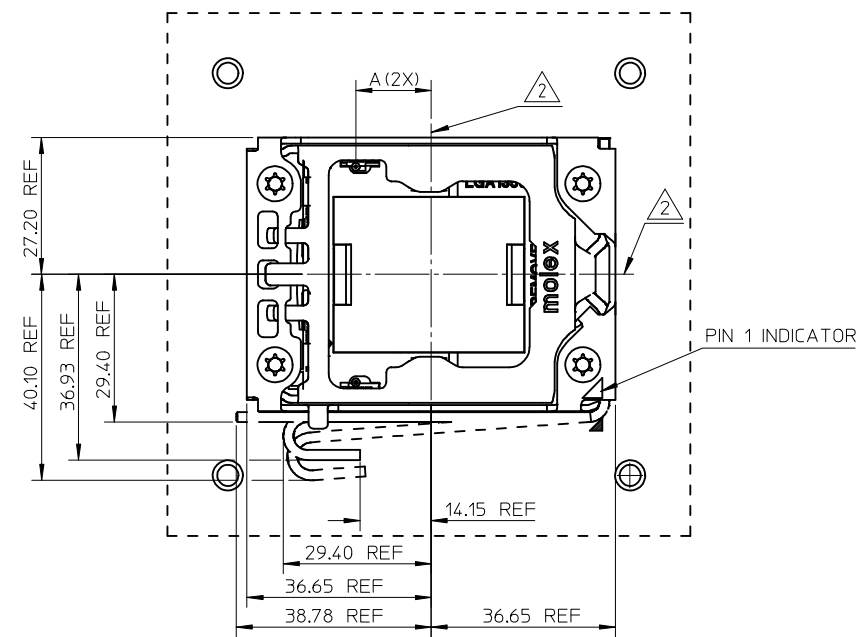
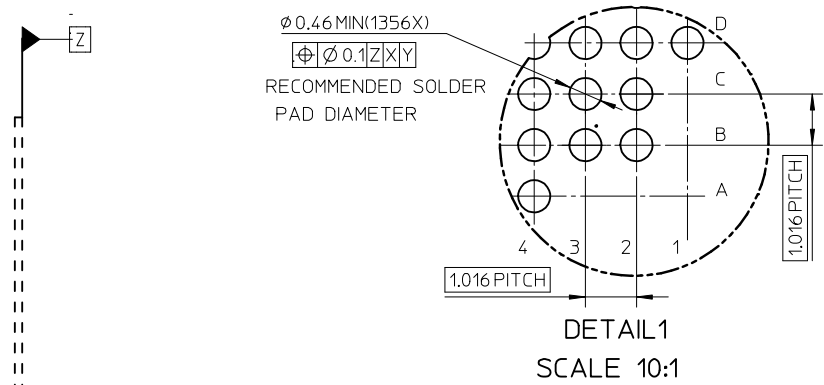




RECOMMEND PCB LAYOUT  
THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
  - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
  - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
  - SOCKET PIN 1 INDICATOR.
  - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
  - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.



SOCKET ON PCB(FOR REFERENCE ONLY)  
LOAD PLATE IS NOT LOCKED

<b>NEW RELEASED</b> IEC NO: SH2013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_{\Delta} = 0$ $F_{\square} = 0$ $F_{\ominus} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>	SCALE <b>1:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY YXZHENG	DATE 2012/09/24	TITLE <b>LGA1356-3 SOCKET(B3) FULL ASSEMBLY</b>			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY AYIN	DATE 2013/02/04	<b>molex</b>			
		ANGULAR ± 1 °		MATERIAL NO. <b>SEE PAGE 1</b>		DOCUMENT NO. <b>SD-47594-200</b>	SHEET NO. <b>3 OF 3</b>		